MULTIPAK ELECTRONICS INDIA PVT LIMITED

No. 1to 4, Kothanur Dinne Main Road, Jambhu Savari Dinne, Banneraghatta Road,
Bangalore – 560 076. PH: 080- 26636005, 26654859 Fax: 26851585.
Email: multipak.sp@gmail.com

COMPANY PROFILE

ABOUT US:

Multipak Electronics India Private Limited has been manufacturing Printed Circuit Board's up to 14 Layer's, for various sectors in electronics field Since 1991.

PROMOTERS:

Mr.S. Purushotham Raju
Mr. S.Bala Raju

PROMOTERS BACK GROUND:

Mr. S.Purushotham Raju is the brain behind Multipak. He had completed his Diploma in Electronics & Tele communication and employed in a pcb industry for about seven years and got sufficient experience in manufacturing Double sided and multi layer printed circuit boards.

Having hand full of experience he had started his own PCB manufacturing plant at Bangalore with a minimum facility in the year of 1991.

MAJOR BUSINESS SECTOR:

Multipak has concentrated their business towards the following sectors.

a) Auto Electronics
b) Telecommunication
c) Automation
d) Power Electronics
e) Defence Electronics (proto types only).

INFRASTRUCTURE GROWTH:

.During 1995 Multipak extended their in house additional facilities like CNC Drilling, Hot Air Leveling & Bare Board Testing.During 2000-2001 Multipak had installed Multi layer Press and started production up to 6 layers for prototype and as well production qty up to 200 nos.During 2002-2003 Multipak increased the capability in multi layers up to 10 layers During 2003-2004 Multipak constructed its second unit at Electronic city, Hosur main road, Bangalore. Its build up area is 25,000 sq.ft. During this period Multipak introduced latest technology called Direct metalization in PTH chemistry and increased their capability in multi layer up to 12 layers.

PRODUCTS:

a) Single sided Glass Epoxy
b) Double sided (0.15 to 3.2 mm Thick)
c) Rigid Multi layers up to 14 Layers.

SERVICE:

Fast Prototyping: 5 working days with special price.

Medium & High Quantities: Standard delivery time 2 – 3 weeks.

Medium & High Quantities: Express delivery 1 week with special price.

QUALITY:

Multipak has fabrication and quality control Expertise apart from promoters.
I S O – 9001: 2000 certified
CACT & ITI Approvals.
LCSO under process

CUSTOMER SUPPORT:

Multipak also provides assistance & solutions in designing & engineering the printed circuit board for customer product.

ENVIRONMENT:

Multipak sincerely respect the environment by providing all treatment plants as per pollution control board specifications to ensure a clean and safe world for future generations.

PRODUCT CAPABILITY:

Maximum Board Size D/S	: 600 x 450 mm
Maximum Board Size M.L.B	: 500 x 450 mm
Maximum Board Thickness MLB/D/S	: 3.20 mm
(On Request 8 mm in MLB)	
Minimum Board Thickness D/S	: 0.15 mm
Minimum Board Thickness MLB	: 0.80 mm

MINIMUM LINES & SPACING :

Lines – Internal (.5 oz base copper)	: 6 mill
Lines – Internal (1 oz base copper)	: 8 mill
Lines – Internal (2 oz base copper)	:12 mill
Spaces – Internal (.5 oz base copper)	: 8 mill
Spaces – Internal (1 oz base copper)	: 10 mill
Spaces – Internal (2 oz base copper)	: 12 mill
Lines – External (0.5 oz base copper)	: 8 mill
Lines – External (1 oz base copper)	: 8 mill
Lines – External (2 oz base copper)	:10 mill
Spaces – External (0.5 oz base copper)	: 8 mill
Spaces – External (1 oz base copper)	: 8 mill
Spaces – External (2 oz base copper)	: 12 mill
Minimum Finished Hole	:16 mill PTH
Maximum layer count – Rigid	:12 layer
Maximum Aspect Ratio:	: 6:1.
Through Hole Copper Thickness	: 25 microns (minimum)
Minimum Angular Ring	: 50 microns
Minimum Average Copper Plating	: 18 micron,20 microns Average
Minimum HAL	: 3 microns
Gold Edge Connector Thickness	: 0.7 – 1.2 microns
Selective Gold Thickness	: 0.3 - 0.6 microns
Immersion Gold Thickness	: 0.05 - 0.1 microns
Nickel Thickness	: 3 – 5 microns
Routing Tolerance	: +/- 150 microns
Hole to Edge Location	: +/- 0.3 mm
V-Groove Angles	: 30/45/60.
Web Thickness	: 1/3
Bare Board Test Voltage	: 40 V
Standard Routing Dia	: 2.4 mm
